

ABSTRACT OF THE DISCLOSURE

5 A semiconductor device includes a semiconductor package, a
substrate provided under the semiconductor package, a metal substrate
provided on the semiconductor package, and a fixing member positioning
the semiconductor package and the metal substrate on the substrate. The
10 substrate is provided with a hole passing through the substrate. A portion
of the fixing member is inserted into the hole and a tip of the fixing member
contacts a fourth terminal. Semiconductor package has a first main
surface, a second main surface provided opposite to the first main surface,
15 and a first terminal provided at the first main surface.